

# Harvatek Surface Mount LEDs Data Sheet F10Q1TX--20P000242U1930

Official Product	HT Part No. F10Q1TX20P000242U1930				
Tentative Product	*******				
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 1/17	



DISCLAIMER	3
LIFE SUPPORT POLICY	3
PRODUCT SPECIFICATION	4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPECIFICATIONS:	5
SPECIFICATIONS RANGE	6
CHROMATICITY COORDINATE:	8
PRODUCT FEATURES	9
ELECTRO-OPTICAL CHARACTERISTICS	9
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERELOW SOLDERING	
ABSOLUTE MAXIMUM RATINGS	
PRECAUTION FOR USE	11
PACKAGING	12
TAPE DIMENSION	
PACKING	
DRY PACKBAKING	
PRECAUTIONS	
HANDLING OF SILICONE RESIN LEDS	15
REFLOW SOLDERING	
Reworking	
CLEANING	
REVISION HISTORY	17

Official Product	HT Part No. F10Q1TX20P000242U1930					
Tentative Product	*******	***********				
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 2/17		



#### **DISCLAIMER**

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

## Life Support Policy

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Official Product	HT Part No. F10Q1TX20P000242U1930				
Tentative Product	*******				
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 3/17	



#### **Product Specification**

Item	Specification	Material	Quantity			
Luminous	950-1440 mcd					
Intensity(Iv)	@20mA/ T <sub>S</sub> = 25°C ;Tolerance:±10%					
Chromaticity	As page 6 & 7					
Coordinate	@20mA/ T <sub>S</sub> = 25°C; Tolerance:±0.005	@20mA/ T <sub>S</sub> = 25°C; Tolerance: ±0.005				
Vf	2.8~3.5 V					
	@20mA/ T <sub>S</sub> = 25°C ;Tolerance:±0.05V					
Ir	< 10 μA @ V <sub>R</sub> = 5 V					
Resin	Yellow	Silicone Resin				
Carrier tape	According to EIA 481-1A specs	Conductive black tape	2000pcs per reel			
Reel	According to EIA 481-1A specs	Conductive black				
Label	HT standard					
Packing bag	250x230mm	Aluminum laminated bag/	One reel one bag			
		no-zipper				
Carton	HT standard	Paper	Non-specified			

#### Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, CIE and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

\*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

#### ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

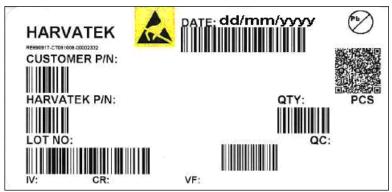
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Official Product	HT Part No. F10Q1TX20P000242U1930				
Tentative Product	*********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 4/17	



## **Label Specifications:**



## ■ Harvatek P/N

F 10Q 1 TX-- 20P- 0001 42

Product	Package	Dice Qty	Color	Current	Series Number	Taping
FL	3.8(L)x1.0(W)x0.6(H) mm	1:Single	TX:White	20mA	X001~XZZZ	1.Taping style
						2. Qty

## Lot No.:

1	2	3	4	5	6	7	8	9	10
E	1	Α	1	Α	2	2	L	1	2
Cod	e 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	2
Internal Tra	acing Code	2020-L 2021-M 2022-P 2023-Q  2026-T 2027-V  2030-Y 2031-Z	1:Jan. 2:Feb.  A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C  26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000~ZZZ	

Official Product	HT Part No. F10Q1TX20P000242U1930				
Tentative Product	*******				
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 5/17	



# Specifications Range.

# ■ Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range		
	Y12	950-1000 mcd		
	Y21	1000-1050 mcd		
	Y22	1050-1125 mcd		
TX	Z11	1125-1200 mcd		
	Z12	1200-1270 mcd		
	Z21	1270-1350 mcd		
	Z22	1350-1440 mcd		

Note: It maintains a tolerance of ±10% on luminous intensity

Official Product	HT Part No. F10Q1TX20P000242U1930					
Tentative Product	*********	*******				
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 6/17		



## Color Bin:

	Х	Y		Х	Y
	0.2600	0.2500		0.2660	0.2420
GCA	0.2520	0.2360	FCA	0.2580	0.2280
GCA	0.2580	0.2280	FCA	0.2640	0.2200
	0.2660	0.2420		0.2720	0.2340
	0.2680	0.2640		0.2740	0.2560
GDA	0.2600	0.2500	FDA	0.2660	0.2420
GDA	0.2660	0.2420	FDA	0.2720	0.2340
	0.2740	0.2560		0.2800	0.2480
	0.2760 0.2780		0.2820	0.2700	
GEA	0.2680	0.2640	FEA	0.2740	0.2560
GEA	0.2740	0.2560	FEA	0.2800	0.2480
	0.2820	0.2700		0.2880	0.2620
	0.2840	0.2920	FHA	0.2900	0.2840
GHA	0.2760	0.2780		0.2820	0.2700
GHA	0.2820	0.2700	ГПА	0.2880	0.2620
	0.2900	0.2840		0.2960	0.2760
	0.2920	0.3060		0.2980	0.2980
GIA	0.2840	0.2920	FIA	0.2900	0.2840
GIA	0.2900	0.2840	FIA	0.2960	0.2760
	0.2980	0.2980		0.3040	0.2900
	0.3000	0.3200		0.3060	0.3120
GJA	0.2920	0.3060	FJA	0.2980	0.2980
GJA	0.2980	0.2980	FJA	0.3040	0.2900
	0.3060	0.3120		0.3120	0.3040

Note: It maintains a tolerance of x, y  $\pm 0.005$ 

Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
without advance notice. F	Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		Version of 1.0	Page 7/17

# **Chromaticity Coordinate:**



# ■ Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range	
	H1	2.8-2.9 V	
	H2	2.9-3.0 V	
	НЗ	3.0-3.1 V	
TX	H4	3.1-3.2 V	
	J1	3.2-3.3 V	
	J2	3.3-3.4 V	
	J3	3.4-3.5 V	

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 8/17



## **Product Features**

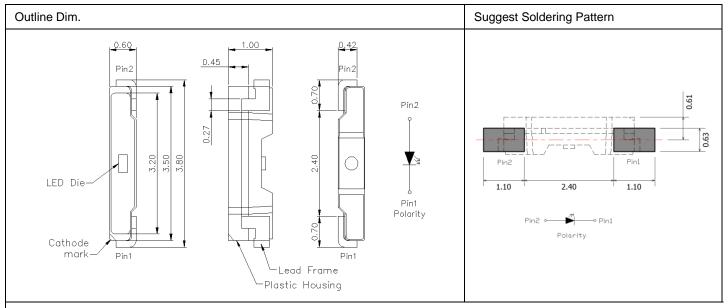
## **Electro-Optical Characteristics**

 $(T_{Soldering}, 25\,^{\circ}C)$ 

Series	Emitting Color	Material	$V_F(V)$		Chromaticity Coordinate	I <sub>V</sub> (mcd)	Viewing
Series	Emitting Color	Material	typ	max	x,y	Typical	Angle $2\theta \frac{1}{2}$
F10Q1TX	White	InGaN	3.2 3.5		x=0.2830,y=0.2700	1020	120

# Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)



Soldering terminals may shift in the x, y direction.

## **Absolute Maximum Ratings**

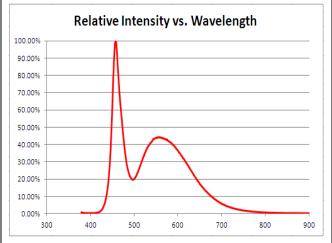
Series	P <sub>D</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)
Color	Power Dissipation	Forward Current	Pulse Forward	Operating	Storage
Color	Power Dissipation		Current	Temperature	Temperature
TX	105	30	35	-40~+85	-40~+100

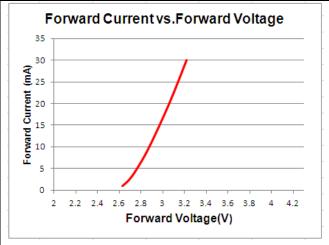
 $<sup>^{\</sup>star}$  Condition for I<sub>FP</sub> is pulse of 1/10 duty and 0.1msec width

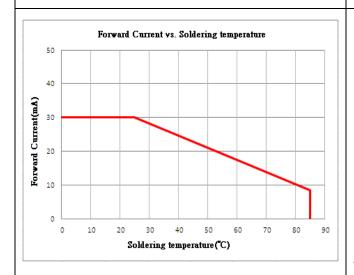
Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 9/17

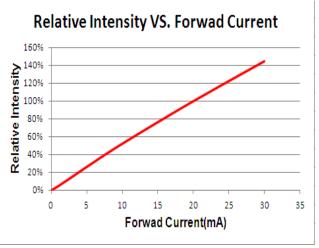


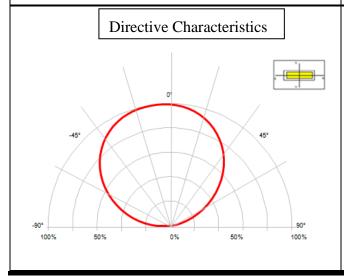
# **Characteristics of F10Q1TX**

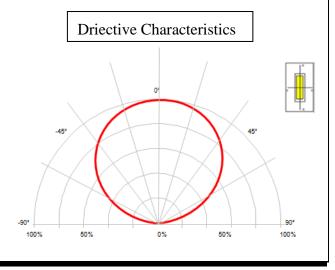












Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 10/17



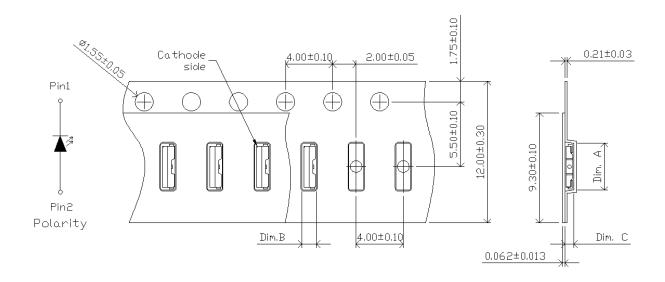
#### **Precaution for Use**

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs. If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs. Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

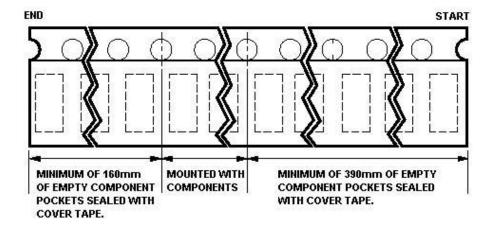
Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	********			
	ect to changes for improvement Proprietary data, drawings, company erved.	11/15/2022	Version of 1.0	Page 11/17



# Packaging Tape Dimension



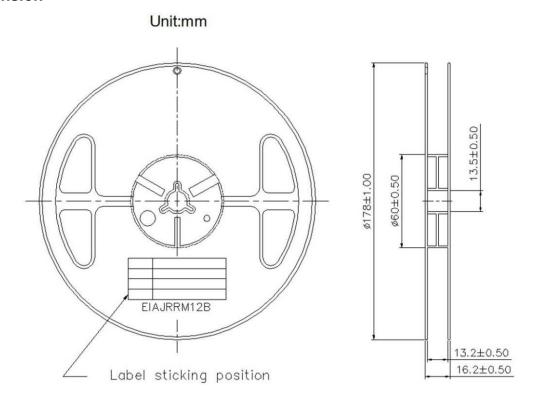
Dim. A	Dim. B	Dim. C	Qty/Reel
4.0±0.10	1.35±0.10	0.78±0.10	2K



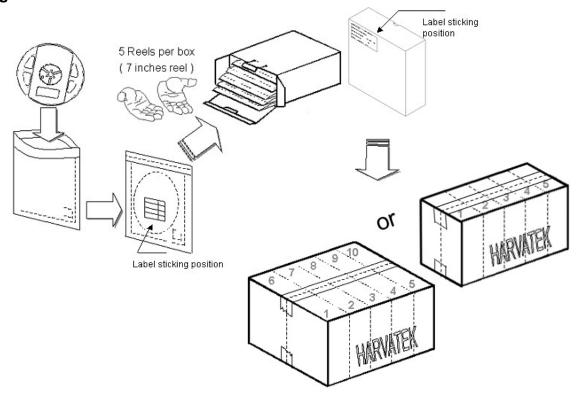
Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 12/17



## **Reel Dimension**



# **Packing**



5 or 10 boxes per carton is available depending on shipment quantity.

Official Data And Educative conficence				
Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company		11/15/2022	Version of 1.0	Page 13/17
confidential all rights reserved.		11/13/2022	version or 1.0	Tage 15/17

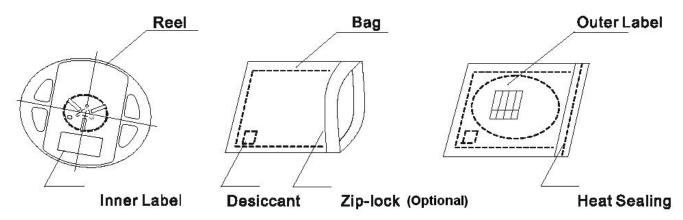


## **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A umidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



## **Baking**

It's recommended to bake before soldering once the pack is unsealed open & re-sealed after 4 weeks. The conditions are as followings:

- 1.  $60 \pm 3^{\circ}$ C×(12~24hrs) and < 5% RH, taped reel type
- 2. 100±3°C×(45min~1hr), bulk type
- 3. 130±3<sup>o</sup>C×(15~30min), bulk type

#### **Precautions**

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product	HT Part No. F10Q1TX20P000242U1930				
Tentative Product	******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 14/17	



## **Handling of Silicone Resin LEDs**

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should mot be used to pierce the sealing compound.



Figure 1

In general, LEDs should only be handled from the side. By the way ,this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

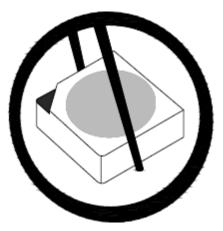


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the from of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is large than LEDs reflector area.

Official Product HT Part No. F10Q1TX20P000242U1930				
Tentative Product	*******	*****		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 15/17

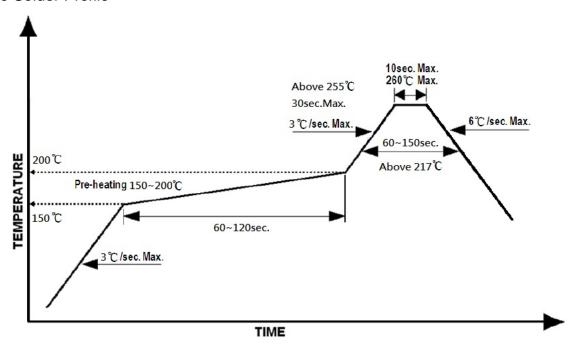


## **Reflow Soldering**

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217 °C ,60~150sec
- 2. Peak temp.:260 <sup>O</sup>CMax.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never take next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measuring on the surface of the LED terminal) is following:

#### Lead-free Solder Profile



#### Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

### Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter</li>
- Curing: 100 <sup>O</sup>C max, <3min</li>

Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*******	*****		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 16/17



## **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

### **Revision History**

The vision in story					
Rev.	Descriptions	Date	Page		
1.0	-	11/15/2022	-		

Official Product	HT Part No. F10Q1TX20P000242U1930			
Tentative Product	*********	*****		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		11/15/2022	Version of 1.0	Page 17/17